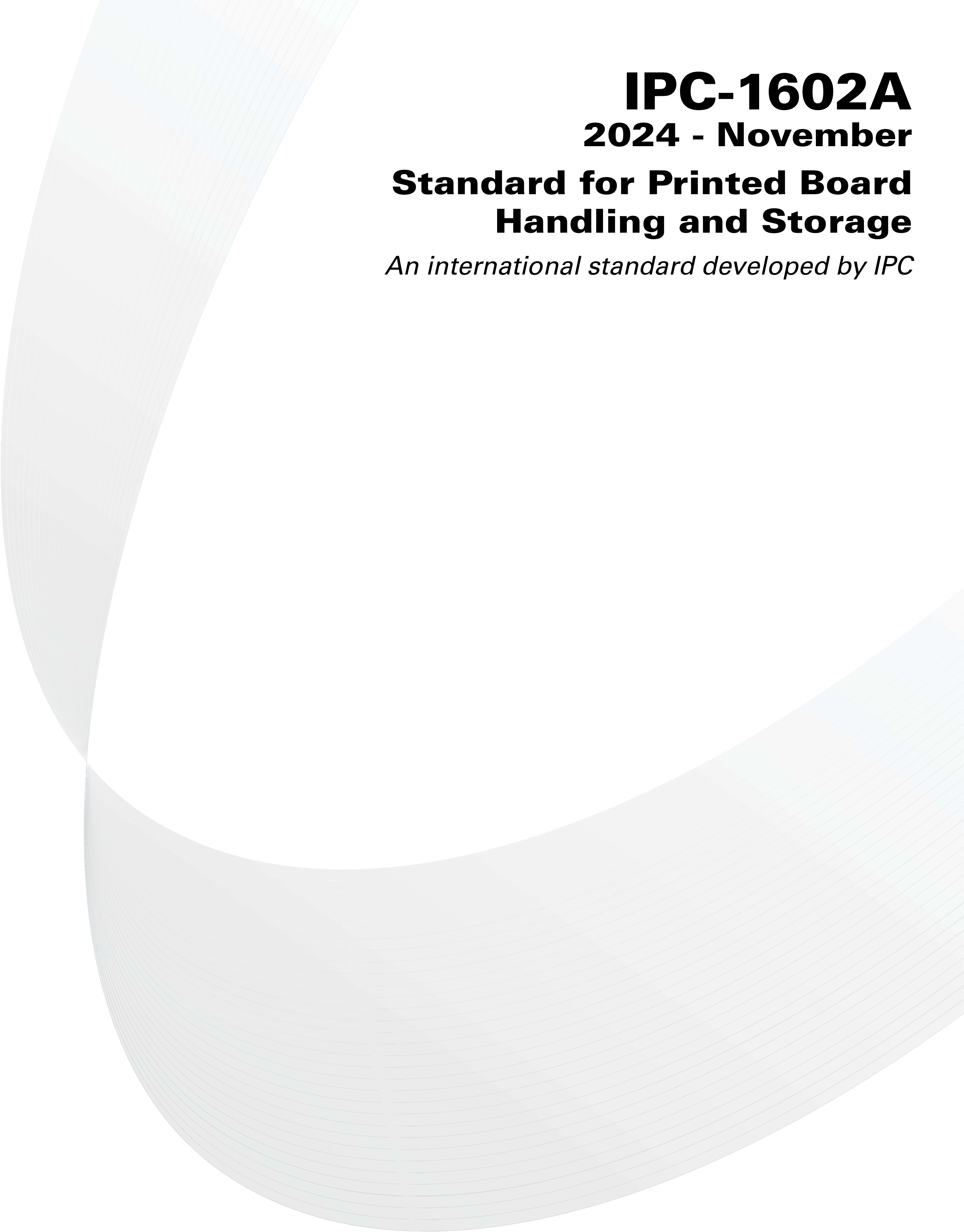

IPC-1602A

2024 - November

Standard for Printed Board Handling and Storage

An international standard developed by IPC

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Standard for Printed Board Handling and Storage

Developed by the Printed Board Storage and Handling Subcommittee (D-35) of the Rigid Printed Board Committee (D-30) of IPC

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